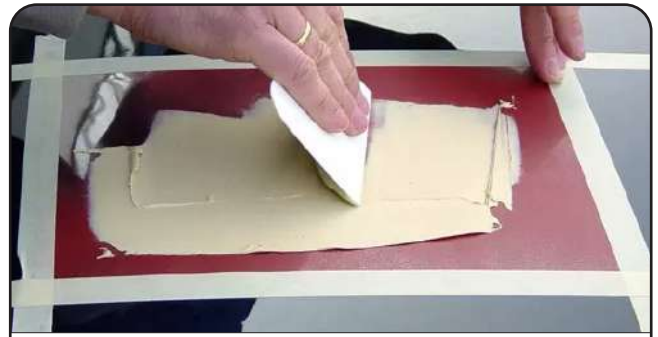


HOLLOW GLASS BEADS



RESINS AND ADHESIVES



POLYESTER AND EPOXY PUTTIES



ENGINEERING PLASTICS



WATER PROOFING

MMSC Hollow Glass Beads/Microsphere.

Resin extension within polymers emerges as a pivotal driver for cost efficiency across various industries. This enhancement yields a cascade of benefits such as amplified solids content leading to diminished VOC levels. Its applications span a wide spectrum, serving as an emulsion explosives sensitizer while enhancing mold and flow dynamics in thermoset scenarios. Furthermore, it bolsters thermal cycling properties in coatings and composites by fortifying insulation factors, thus enabling higher solid loading without the typical viscosity surge. Its versatility extends to acrylic patching and filling compounds, finding resonance in markets like construction, automotive, composites, coatings, and oil well cements. Notably, this augmentation minimizes defects by facilitating excellent mold flow and uniform dispersion, concurrently reducing compound density and viscosity. Its impact resonates in amplified acoustic and thermal insulation, along with cost reduction and improved handling in flexible compounds. Moreover, it refines the structure of syntactic compounds, fostering a more uniform, closed-cell configuration, ultimately leading to cost savings through reduced sandpaper consumption and labor efficiencies in putty applications.

- **Improve flow properties**
- **High resin displacement**
- **Low shrinkage and warpage**
- **Better stress distribution**
- **Excellent chemical resistance**